

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Daniel Yap,)	Re: Information Disclosure
et al.)	Statement
)	
Serial No.: Not yet assigned)	
Filed: concurrently herewith)	
)	
Divisional of USSN 09/648,689)	
filed on August 25, 2000)	Our Ref: B-3858DIV 620913-1
)	
For: "OPTICAL BOND-WIRE)	
INTERCONNECTIONS AND A METHOD FOR)	
FABRICATION THEREOF")	Date: August 26, 2003

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the Applicant's duty to disclose information which may be material to the examination of this application, the undersigned respectfully requests that the documents cited by the Examiner and/or submitted by the Applicant in connection with U.S. Serial No. 09/648,689 filed on August 25, 2000 (the parent of the Applicants' subject application) be considered by the Examiner before issuing the first Office Action on the merits.

For the Examiner's convenience, Form PTO-1449 (modified) is enclosed herewith listing the documents cited by the Examiner and/or submitted by the Applicant in connection with U.S. Serial No. 09/648,689.

The filing of this Information Disclosure Statement (IDS) shall not be construed as a representation that a search has been made (37 C.F.R. 1.97(g)), an admission that the information cited is, or is considered to be, material to patentability, or that no other material information exists.

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If any fees are due, please charge our Deposit Account No. 12-0415 or credit any overpayment to our Account No. 12-0415. No fees should be due because this Information Disclosure Statement is being filed concurrently with the above-identified U.S. patent application.

The filing of this Information Disclosure Statement shall not be construed as an admission against interest in any manner. (Notice of January 9, 1992, 1135 O.G. 13-25, at 25.)

The person making this statement is the practitioner who signs below on the basis of information supplied by an individual associated with the filing and prosecution of this application (37 C.F.R. § 1.56(c)) and on the basis of information in the practitioner's file.

Respectfully submitted,



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Enclosures: Form PTO-1449 (modified) (2 pages)

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Form PTO-1449 (Modified)	ATTY DOCKET NO. B-3858DIV 620913-1	U.S. SERIAL NO. not yet assigned
LIST OF PATENTS AND PUBLICATIONS STATEMENT	APPLICANT(S) Daniel Yap, et al.	
	FILING DATE concurrently herewith	GROUP not yet assigned

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUB-CLASS	FILING DATE or 102(e) DATE IF APPROPRIATE
	3,963,920	06/1976	Palmer	250	239	
	4,358,676	11/1982	Childs, et al.	250	214R	
	5,466,558	11/1995	Sasaki	430	321	
	5,668,386	09/1997	Makiuchi, et al.	257	184	
	6,187,515	02/2001	Tran, et al.	385	39	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	PUBLICATION DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO
	0 816 878 A2	01/1998	EP			
	0 846 966 A2	06/1998	EP			
	61-121014	09/1986	JP			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	Abstract of JP 61-121014, <i>Patent Abstracts of Japan</i> , 1986.
	Abstract of JP 03-256011, <i>Patent Abstracts of Japan</i> , 1991.
	Balliet, L., et al., "Built-in Alignment Circuit for Fiber-Optic Silicon Optical Bench," <i>IBM Technical Disclosure Bulletin</i> , Vol. 24, No. 2, pp. 1158-1160 (July 1981).
	Ghatak, A., et al., <i>Introduction to Fiber Optics</i> , Cambridge Univ. Press, pp. 221-225 (1998).
	Imler, W.R., "Precision Flip-Chip Solder Bump Interconnects for Optical Packaging," <i>IEEE Transactions on Components, Hybrids, and Manufacturing Technology</i> , Vol. 15, No. 6 (Dec. 1992), pp. 997-981.

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	Kawanobe, T., et al., "Solder Bump Fabrication by Electrochemical Method for Flip Chip Inteconnection," <i>IEEE</i> , Publication CH1671-7/81/0000 (1981), pp. 149-155.
	Louderback, D.A., et al., "Modulation and Free-Space Link Characteristics of Monolithically Integrated Vertical-Cavity Lasers and Photodetectors with Microlenses," <i>IEEE Journal of Selected Topics in Quantum Electronics</i> , Vol. 5, No. 2 (1999), pp. 27-35.

EXAMINER	DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.